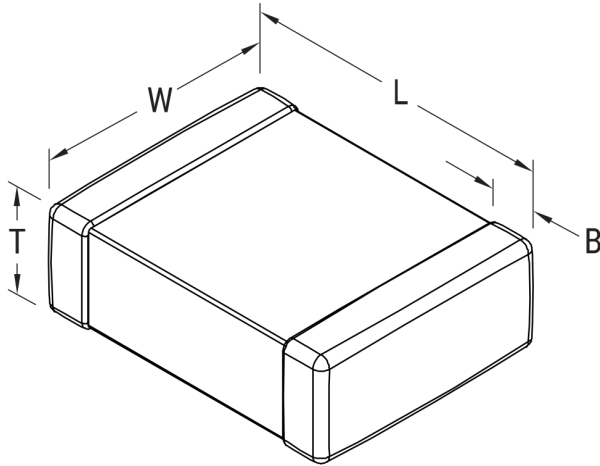


CBR02C889C3GAC

CBR-SMD RF COG, Ceramic, 8.8 pF, ± 0.25 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201



Click [here](#) for the 3D model.

Dimensions

Chip Size	0201
L	0.6mm ± 0.03 mm
W	0.3mm ± 0.03 mm
T	0.3mm ± 0.03 mm
B	0.15mm ± 0.05 mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	15000

General Information

Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	0.3 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	8.8 pF
Capacitance Tolerance	± 0.25 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.174%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	576

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